



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY DRAWING

PCB VIEWED FROM BOTTOM SIDE	BOARD #	TIDN-02540	REV	ET	SAR REV	Not in versioncontrol
LAYER NAME = H6 Assembly Bottom	TID #	TIDN-02540	JONKNE ->			
PLOT NAME = Bottom Assembly Drawing	GENERATED	24-Nov-17	4:26:00 PM			

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